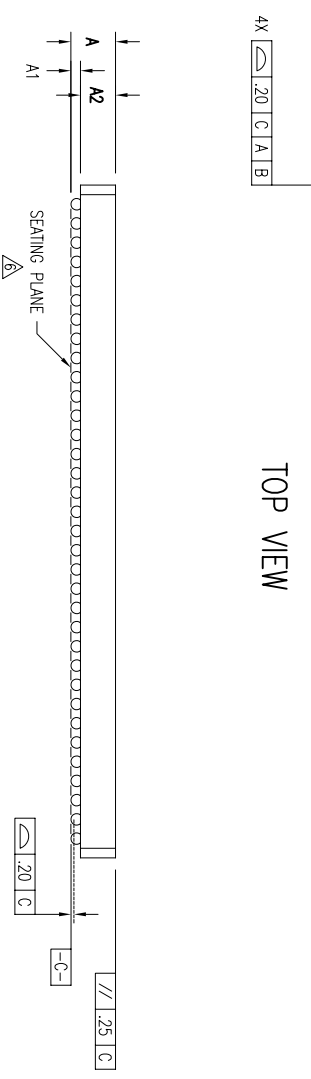
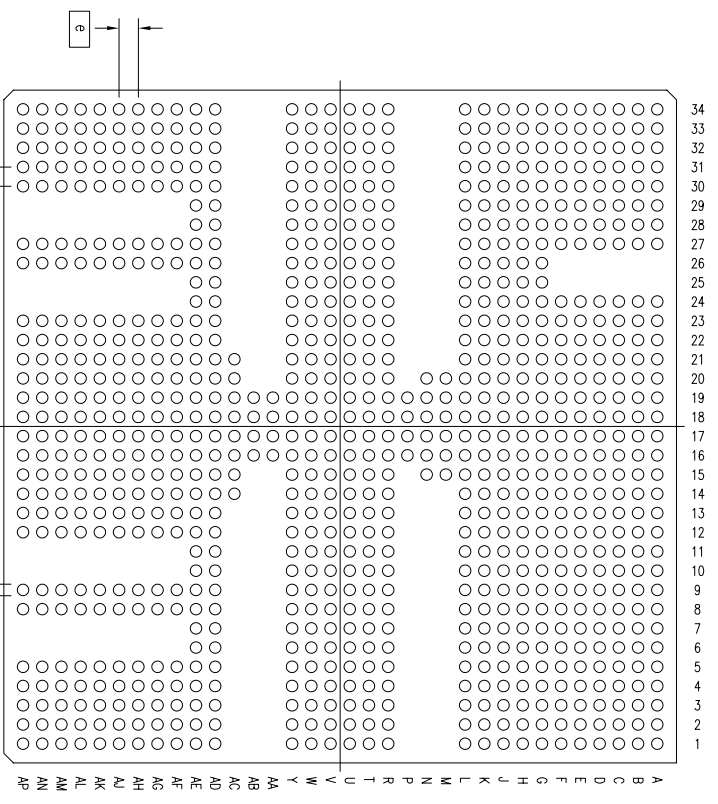
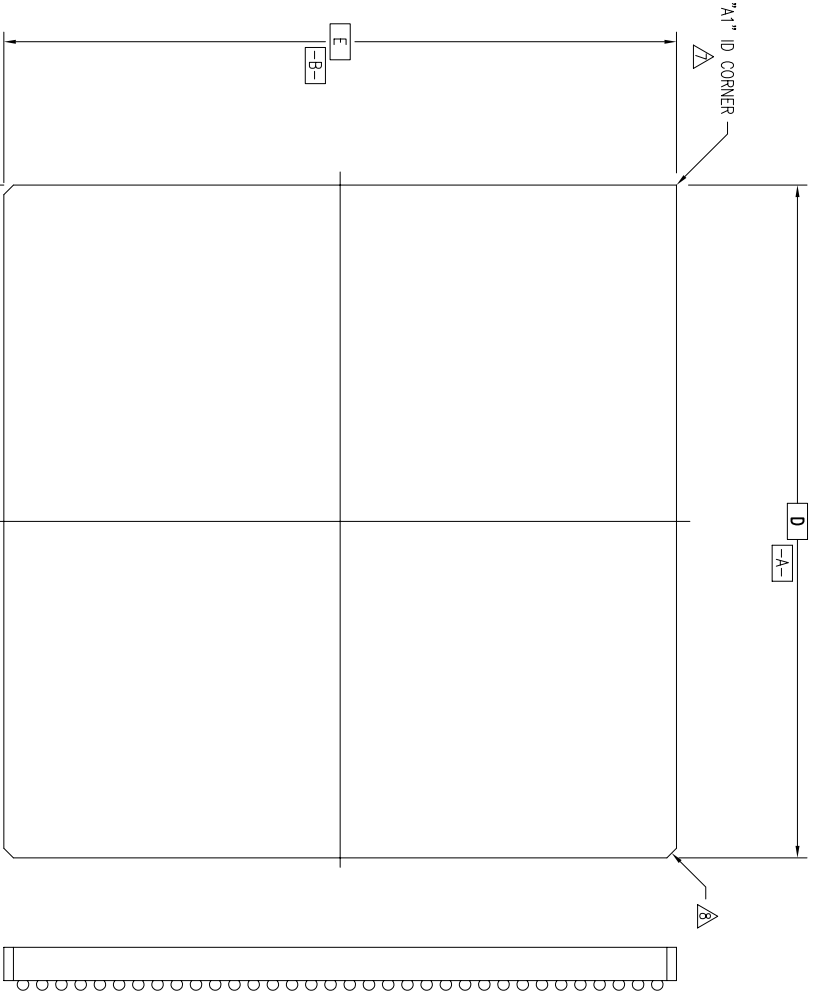


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	07/08/03	TV
01	ADDED ROHS BR	06/22/09	P.Pqk
02	COMBINE POD & LAND PATTERN	06/03/13	KS

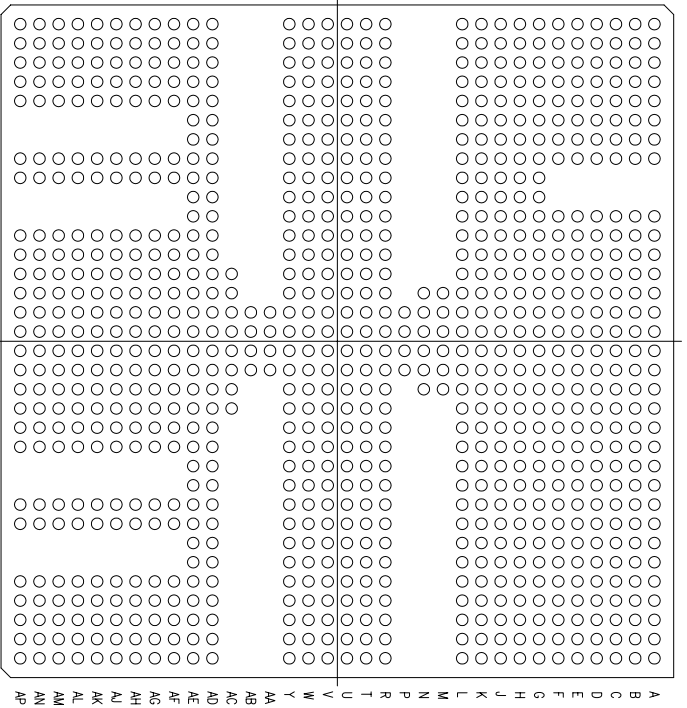


TOLERANCES UNLESS SPECIFIED	
DECIMAL	±
ANGULAR	±
XXX±	
XXXX±	
XXXX±	
APPROVALS	DATE
DRAWN 379	05/15/03
CHECKED	
SIZE C	DRAWING No. PSC-4121
DO NOT SCALE DRAWING	SHEET 1 OF 3

IDT Integrated Device Technology, Inc.
 6024 Silver Creek Valley Road
 Fremont, CA 94538
 (510) 593-9345
 FAX (510) 593-9345
 WWW.IDT.COM TEL: (408) 284-4591 TWC: 916-358-2070

TITLE: BU/BR 900 PACKAGE OUTLINE
 35.0 X 35.0 mm BODY
 1.0 mm BALLPITCH FC8GA

34
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1



BOTTOM VIEW
(BALL SIDE VIEW)

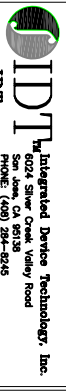
SYMBOL	JEDEC VARIATION			NOTE
	MIN	NOM	MAX	
A	—	—	3.42	
A1	.30	—	—	
A2	2.16	—	2.82	
D	35.00 BSC			
E	35.00 BSC			
M	34 (DEPOPULATED)			3
N	900			4
e	1.00 BSC			
b	.50	.60	.70	5
CENTER BALL MATRIX	N/A			

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	07/08/03	TV
01	ADDED ROHS BR	06/22/09	P-Park
02	COMBINE POD & LAND PATTERN	06/03/13	KS

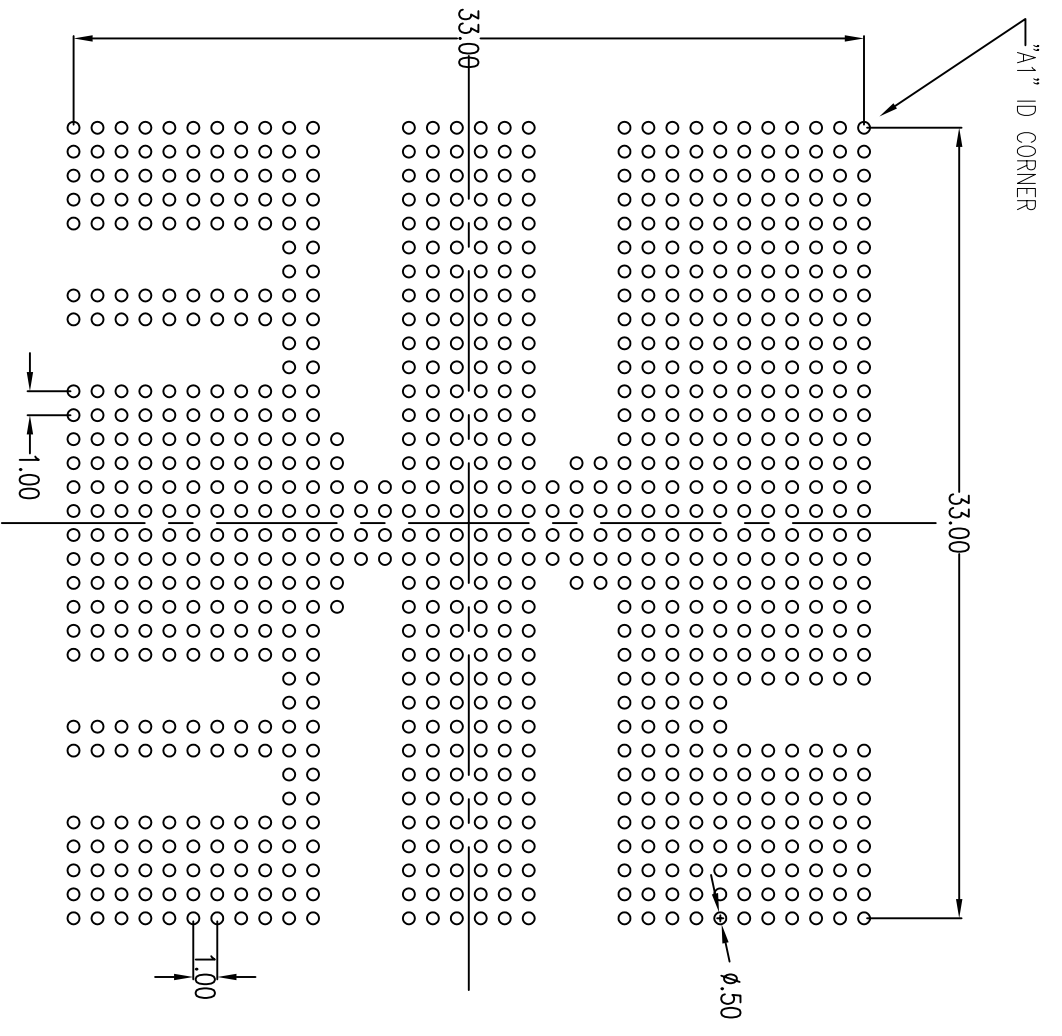
NOTES:

- 1 ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- 2 "e" REPRESENTS THE BASIC SOLDER BALL GRID PITCH
- 3 "M" REPRESENTS THE MAXIMUM SOLDER BALL MATRIX SIZE
- 4 "N" REPRESENTS THE BALLOON NUMBER
- 5 DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM \square -C-
- 6 SEATING PLANE AND PRIMARY DATUM \square -C- ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS
- 7 "A1" ID CORNER MUST BE IDENTIFIED BY CHAMFER, INK MARK, METALLIZED MARKING, INDENTATION OR OTHER FEATURE ON PACKAGE BODY
- 8 EXACT SHAPE OF EACH CORNER IS OPTIONAL
- 9 ALL DIMENSIONS ARE IN MILLIMETERS

TOLERANCES UNLESS SPECIFIED		DECIMAL ANGULAR	
XXX±	±	XXXX±	±
APPROVALS	DATE	TITLE	
DRAWN 779	05/15/03	BL/BR 900 PACKAGE OUTLINE	
CHECKED		35.0 X 35.0 mm BODY	
		1.0 mm BALLPITCH FCBGA	
SIZE	DRAWING No.	PSC-4121	REV
C			02
DO NOT SCALE DRAWING			SHEET 2 OF 3




REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
00	INITIAL RELEASE	07/08/03	TV
01	ADDED ROHS BR	06/22/09	P.Park
02	COMBINE POD & LAND PATTERN	06/03/13	KS



RECOMMENDED LAND PATTERN DIMENSION

NOTE:

- 1) ALL dimensions are in mm, Angles in degrees.
- 2) Top down view, as view on PCB.
- 3) NSMD Land Pattern Assumed
- 4) Land Pattern Recommendation as per IPC-7351B generic requirement for surface mount design and Land Pattern.

TOLERANCES UNLESS SPECIFIED		 Integrated Device Technology, Inc. 6024 Silver Creek Valley Road Fremont, CA 94538 Phone: (408) 298-8345 Fax: (408) 298-8591 TW: 916-358-2070 www.idt.com	
DECIMAL	±	ANGULAR	
XXX.X			
XXXX			
XXXXX			
APPROVALS	DATE	TITLE	
DRAWN 97J	06/15/03	BL/BR 900 PACKAGE OUTLINE	
CHECKED		35.0 X 35.0 mm BODY	
		1.0 mm BALLPITCH FBGA	
		SIZE DRAWING NO. PSC-4121	REV 02
		DO NOT SCALE DRAWING	SHEET 3 OF 3